

### **General Description**

The AAT8515 is a low threshold P-channel MOSFET designed for the battery, cell phone, and PDA markets. Using AnalogicTech's ultra-high-density MOS-FET process and space-saving, small-outline, J-lead package, performance superior to that normally found in a TSOP-6 footprint has been squeezed into the footprint of an SC70JW-8 package.

## **Applications**

- Battery Packs
- Battery-Powered Portable Equipment
- Cellular and Cordless Telephones

## **Absolute Maximum Ratings**

 $T_A = 25^{\circ}C$ , unless otherwise noted.

| Symbol           | Description  |                     | Value      | Units |  |
|------------------|--|---------------------|------------|-------|--|
| V <sub>DS</sub>  | Drain-Source Voltage   |                     | -20        | V     |  |
| V <sub>GS</sub>  | Gate-Source Voltage  |                     | ±12        | v     |  |
| 1                | Continuous Drain Current @ T <sub>J</sub> = 150°C <sup>1</sup> | $T_A = 25^{\circ}C$ | ±5.4       |       |  |
| I <sub>D</sub>   |  | $T_A = 70^{\circ}C$ | ±4.3       | А     |  |
| I <sub>DM</sub>  | Pulsed Drain Current <sup>2</sup>                              |                     | ±32        | A     |  |
| I <sub>S</sub>   | Continuous Source Current (Source-Drain Diode) <sup>1</sup>    | -1.5                |            |       |  |
| TJ               | Operating Junction Temperature Range                           |                     | -55 to 150 | °C    |  |
| T <sub>STG</sub> | Storage Temperature Range                                      |                     | -55 to 150 | °C    |  |

## **Thermal Characteristics**<sup>1</sup>

| Symbol              | Description                      |                       | Тур | Мах  | Units |  |
|---------------------|----------------------------------|-----------------------|-----|------|-------|--|
| $R_{	ext{	heta}JA}$ | Junction-to-Ambient Steady State |                       | 100 | 120  | °C/W  |  |
| R <sub>0JA2</sub>   | Junction-to-Ambient t<5 Seconds  |                       | 61  | 73.5 | °C/W  |  |
| R <sub>0JF</sub>    | Junction-to-Foot                 |                       | 33  | 40   | °C/W  |  |
| P <sub>D</sub>      | Maximum Power Dissipation        | T <sub>A</sub> = 25°C |     | 1.7  | W     |  |
|                     |                                  | $T_A = 70^{\circ}C$   |     | 1.0  | vv    |  |

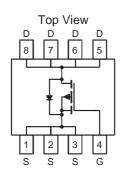
1. Based on thermal dissipation from junction to ambient while mounted on a 1" x 1" PCB with optimized layout. A 5-second pulse on a 1" x 1" PCB approximates testing a device mounted on a large multi-layer PCB as in most applications.  $R_{\theta JF} + R_{\theta FA} = R_{\theta JA}$  where the foot thermal reference is defined as the normal solder mounting surface of the device's leads.  $R_{\theta JF}$  is guaranteed by design; however,  $R_{\theta CA}$  is determined by the PCB design. Actual maximum continuous current is limited by the application's design.

2. Pulse test: Pulse Width = 300µs.

### Features

- Drain-Source Voltage (max): -20V
- Continuous Drain Current<sup>1</sup> (max):
- -5.4A @ 25°C
- Low On-Resistance:  $-35m\Omega @ V_{GS} = -4.5V$ 
  - 60m $\Omega$  @ V<sub>GS</sub> = -2.5V

### SC70JW-8 Package





## **Electrical Characteristics**

 $T_J = 25^{\circ}C$ , unless otherwise noted.

| Symbol              | Description                             | Conditions   | Min  | Тур  | Max   | Units |  |
|---------------------|---|--|------|------|-------|-------|--|
| DC Chara            | DC Characteristics                      |  |      |      |       |       |  |
| BV <sub>DSS</sub>   | Drain-Source Breakdown                  | $V_{GS} = 0V, I_{D} = -250\mu A$   | -20  |      |       | V     |  |
|                     | Voltage                                 |  |      |      |       |       |  |
| R <sub>DS(ON)</sub> | Drain-Source On-Resistance <sup>1</sup> | $V_{GS} = -4.5V, I_{D} = -5.4A$  |      | 27   | 35    | — mΩ  |  |
|                     |   | $V_{GS} = -2.5V, I_{D} = -4.1A$  |      | 46   | 60    |       |  |
| I <sub>D(ON)</sub>  | On-State Drain Current <sup>1</sup>     | $V_{GS}$ = -4.5V, $V_{DS}$ = -5V (pulsed)  | -32  |      |       | А     |  |
| V <sub>GS(th)</sub> | Gate Threshold Voltage                  | $V_{GS} = V_{DS}, I_{D} = -250 \mu A$  | -0.6 |      |       | V     |  |
| I <sub>GSS</sub>    | Gate-Body Leakage Current               | $V_{GS} = \pm 12V, V_{DS} = 0V$  |      |      | ±100  | nA    |  |
| I <sub>DSS</sub>    | Drain Source Leakage Current            | $V_{GS} = 0V, V_{DS} = -20V$   |      |      | -1    | uА    |  |
|                     |   | $V_{GS} = 0V, V_{DS} = -16V, T_{J} = 70^{\circ}C^{2}$                            |      |      | -5 µA | μΛ    |  |
| 9 <sub>fs</sub>     | Forward Transconductance <sup>1</sup>   | $V_{DS} = -5V, I_{D} = -5.4A$  |      | 12   |       | S     |  |
| Dynamic             | Characteristics <sup>2</sup>            |  |      |      |       |       |  |
| $Q_{G}$             | Total Gate Charge                       | $V_{DS} = -15V, R_{D} = 2.3\Omega, V_{GS} = -4.5V$                               |      | 13.6 |       |       |  |
| $Q_{GS}$            | Gate-Source Charge                      | $V_{DS} = -15V, R_{D} = 2.3\Omega, V_{GS} = -4.5V$                               |      | 2.3  |       | nC    |  |
| $Q_{GD}$            | Gate-Drain Charge                       | $V_{DS} = -15V, R_{D} = 2.3\Omega, V_{GS} = -4.5V$                               |      | 5.5  |       |       |  |
| t <sub>D(ON)</sub>  | Turn-On Delay                           | $V_{DS}$ = -15V, $R_{D}$ = 2.3 $\Omega$ , $V_{GS}$ = -4.5V, $R_{G}$ = 6 $\Omega$ |      | 10   |       |       |  |
| t <sub>R</sub>      | Turn-On Rise Time                       | $V_{DS}$ = -15V, $R_{D}$ = 2.3 $\Omega$ , $V_{GS}$ = -4.5V, $R_{G}$ = 6 $\Omega$ |      | 37   |       | ns    |  |
| t <sub>D(OFF)</sub> | Turn-Off Delay                          | $V_{DS}$ = -15V, $R_{D}$ = 2.3 $\Omega$ , $V_{GS}$ = -4.5V, $R_{G}$ = 6 $\Omega$ |      | 36   |       |       |  |
| t <sub>F</sub>      | Turn-Off Fall Time                      | $V_{DS}$ = -15V, $R_{D}$ = 2.3 $\Omega$ , $V_{GS}$ = -4.5V, $R_{G}$ = 6 $\Omega$ |      | 52   |       |       |  |
| Source-D            | rain Diode Characteristics              |  |      |      |       |       |  |
| $V_{SD}$            | Source-Drain Forward                    | $V_{GS} = 0, I_{S} = -5.4A$  |      |      | -1.4  | V     |  |
|                     | Voltage <sup>1</sup>                    |  |      |      |       |       |  |
| ۱ <sub>s</sub>      | Continuous Diode Current <sup>3</sup>   |  |      |      | -1.5  | А     |  |

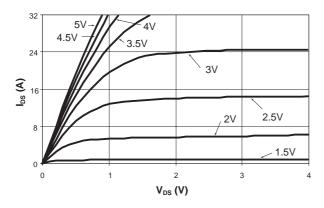
- 1. Pulse test: Pulse Width =  $300\mu$ s.
- 2. Guaranteed by design. Not subject to production testing.

<sup>3.</sup> Based on thermal dissipation from junction to ambient while mounted on a 1" x 1" PCB with optimized layout. A 5-second pulse on a 1" x 1" PCB approximates testing a device mounted on a large multi-layer PCB as in most applications.  $R_{\theta JF} + R_{\theta FA} = R_{\theta JA}$  where the foot thermal reference is defined as the normal solder mounting surface of the device's leads.  $R_{\theta JF}$  is guaranteed by design; however,  $R_{\theta CA}$  is determined by the PCB design. Actual maximum continuous current is limited by the application's design.



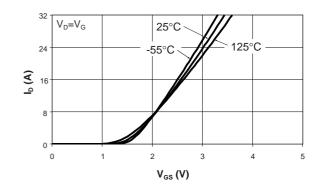
## **Typical Characteristics**

 $T_J = 25^{\circ}C$ , unless otherwise noted.

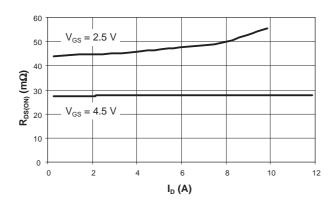


#### **Output Characteristics**

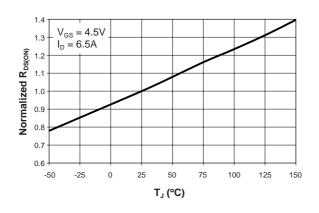
#### **Transfer Characteristics**



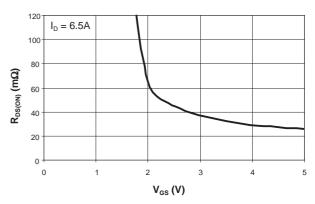
**On-Resistance vs. Drain Current** 



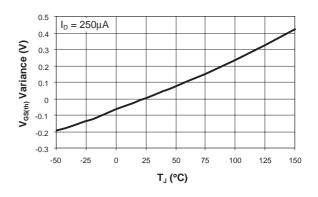
**On-Resistance vs. Junction Temperature** 



**On-Resistance vs. Gate-to-Source Voltage** 



**Threshold Voltage** 

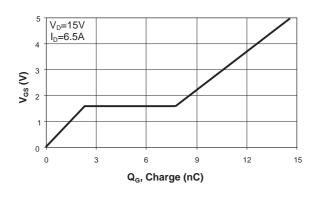




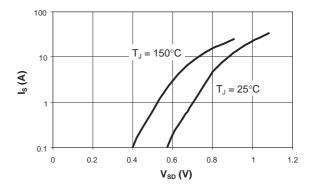
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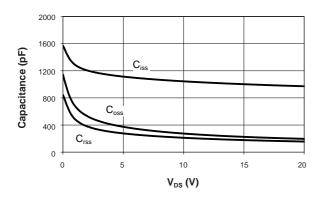
#### Gate Charge



#### Source-Drain Diode Forward Voltage



#### Capacitance



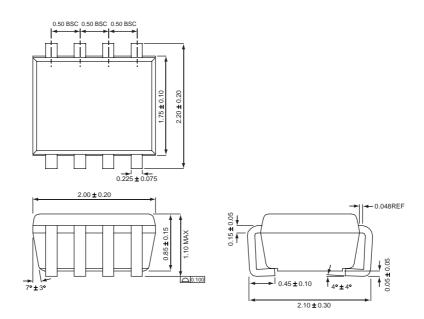


## **Ordering Information**

| Package  | <b>Marking</b> <sup>1</sup> | Part Number (Tape and Reel) <sup>2</sup> |
|----------|-----------------------------|--|
| SC70JW-8 | GTXYY                       | AAT8515IJS-T1                            |

## Package Information





All dimensions in millimeters.

1. XYY = assembly and date code.

2. Sample stock is generally held on part numbers listed in BOLD.



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